

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A glass for a window of a semiconductor package, which is for use as a window material for a semiconductor package made of a plastic and has an average linear expansion coefficient of $120 \times 10^{-7}/^{\circ}\text{C}$ to $180 \times 10^{-7}/^{\circ}\text{C}$ at a temperature of 100 to 300°C and contains Cu and phosphorus oxide in which a wavelength which exhibits a transmittance of 50% is 630 nm or less in terms of a spectral transmittance at a wavelength of 400 to 700 nm when the glass has a thickness of 0.5 mm.

2. (Original) A glass for a window of a semiconductor package, having an average linear expansion coefficient of $120 \times 10^{-7}/^{\circ}\text{C}$ to $180 \times 10^{-7}/^{\circ}\text{C}$ at a temperature of 100 to 300°C and having a U content of 5 ppb or less and a Th content of 5 ppb or less.

3.-5. (Canceled).

6. (Currently Amended) A glass window for a semiconductor package, which is made of the glass recited in claim 1, or 2 or 13.

7. (Currently Amended) A glass window for a semiconductor package, having a lens function and having an average linear expansion coefficient of $120 \times 10^{-7}/^{\circ}\text{C}$ to $180 \times 10^{-7}/^{\circ}\text{C}$ at a temperature of 100 to 300°C and contains Cu and phosphorus oxide in which a wavelength which exhibits a transmittance of 50% is 630 nm or less in terms of a spectral transmittance at a wavelength of 400 to 700 nm when the glass has a thickness of 0.5 mm.

8. (Original) A glass window for a semiconductor package, which is formed of a glass having an average linear expansion coefficient of $120 \times 10^{-7}/^{\circ}\text{C}$ to $180 \times 10^{-7}/^{\circ}\text{C}$ at a temperature

of 100 to 300°C, having a U content of 5 ppb or less and a Th content of 5 ppb or less and containing Cu and phosphorus oxide, in which a wavelength which exhibits a transmittance of 50 % is 630 nm or less in terms of a spectral transmittance at a wavelength of 400 to 700 nm when the glass window has a thickness of 0.5 mm.

9. (Original) The glass window for a semiconductor package as recited in claim 6, which is a precision press-molded product.

10. (Currently Amended) A process for the production of a glass window for a semiconductor package, which comprises precision-press-molding a lens-shaped window material glass made of a glass having an average linear expansion coefficient of $120 \times 10^{-7}/^{\circ}\text{C}$ to $180 \times 10^{-7}/^{\circ}\text{C}$ at a temperature of 100 to 300°C and contains Cu and phosphorus oxide in which a wavelength which exhibits a transmittance of 50% is 630 nm or less in terms of a spectral transmittance at a wavelength of 400 to 700 nm when the glass has a thickness of 0.5 mm.

11. (Original) A semiconductor package comprising the glass window for a semiconductor package recited in claim 6, a semiconductor device and a package encasing the semiconductor device, the glass window having an attaching portion made of a plastic material.

12. (Original) A semiconductor package as recited in claim 11, wherein the semiconductor device is an image-sensing device.

13. (New) A glass for a window of a semiconductor package, which is for use as a window material for a semiconductor package made of a plastic and has an average linear expansion coefficient of $120 \times 10^{-7}/^{\circ}\text{C}$ to $180 \times 10^{-7}/^{\circ}\text{C}$ at a temperature of 100 to 300°C and, the glass contains, by cationic %, 23 to 41 % of P⁵⁺, 4 to 16 % of Al³⁺, 11 to 40 % of Li⁺, 3 to 13 % of Na⁺, 12 to 53 % of R²⁺ (R²⁺ stands for Mg²⁺, Ca²⁺, Sr²⁺, Ba²⁺ or Zn²⁺) and 2.6 to 4.7 % of Cu²⁺ and contains F⁻ and O²⁻ as anionic components.

14. (New) A glass window for a semiconductor package, having a lens function and having an average linear expansion coefficient of $120 \times 10^{-7}/^{\circ}\text{C}$ to $180 \times 10^{-7}/^{\circ}\text{C}$ at a temperature of 100 to 300°C and contains Cu and phosphorus oxide in which a wavelength which exhibits a transmittance of 50% is 630 nm or less in terms of a spectral transmittance at a wavelength of 400 to 700 nm when the glass has a thickness of 0.5 mm

wherein the glass contains, by cationic %, 23 to 41 % of P⁵⁺, 4 to 16 % of Al³⁺, 11 to 40 % of Li⁺, 3 to 13 % of Na⁺, 12 to 53 % of R²⁺ (R²⁺ stands for Mg²⁺, Ca²⁺, Sr²⁺, Ba²⁺ or Zn²⁺) and 2.6 to 4.7 % of Cu²⁺ and contains F⁻ and O²⁻ as anionic components.

15. (New) A process for the production of a glass window for a semiconductor package, which comprises precision-press-molding a lens-shaped window material glass made of a glass having an average linear expansion coefficient of $120 \times 10^{-7}/^{\circ}\text{C}$ to $180 \times 10^{-7}/^{\circ}\text{C}$ at a temperature of 100 to 300°C and contains Cu and phosphorus oxide in which a wavelength which exhibits a transmittance of 50% is 630 nm or less in terms of a spectral transmittance at a wavelength of 400 to 700 nm when the glass has a thickness of 0.5 mm

wherein the glass contains, by cationic %, 23 to 41 % of P⁵⁺, 4 to 16 % of Al³⁺, 11 to 40 % of Li⁺, 3 to 13 % of Na⁺, 12 to 53 % of R²⁺ (R²⁺ stands for Mg²⁺, Ca²⁺, Sr²⁺, Ba²⁺ or Zn²⁺) and 2.6 to 4.7 % of Cu²⁺ and contains F⁻ and O²⁻ as anionic components.